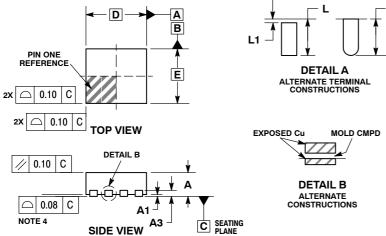
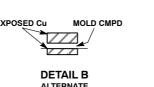
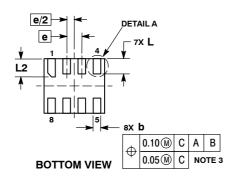


WDFN8 2x1.8, 0.5P CASE 511BU ISSUE O

DATE 18 JAN 2012







- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION 5 APPLIES TO PLATED
 TERMINAL AND IS MEASURED BETWEEN
 0.15 AND 0.20 MM FROM TERMINAL TIP.
 COPLANARITY APPLIES TO THE EXPOSED
- PAD AS WELL AS THE TERMINALS.

| | MILLIMETERS | |
|-----|-------------|------|
| DIM | MIN | MAX |
| Α | 0.70 | 0.80 |
| A1 | 0.00 | 0.05 |
| A3 | 0.20 REF | |
| b | 0.20 | 0.30 |
| D | 2.00 BSC | |
| E | 1.80 BSC | |
| е | 0.50 BSC | |
| L | 0.45 | 0.55 |
| L1 | | 0.15 |
| L2 | 0.55 | 0.65 |

GENERIC MARKING DIAGRAM*



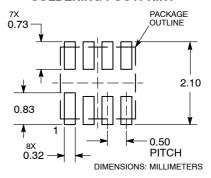
XX = Specific Device Code

M = Date Code

= Pb-Free Device

(Note: Microdot may be in either location) *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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